

OL-LPC11AxxUK

wafer level chip-size package; 20 bumps

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	27-3-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.5	-	2.55	2.6	mm
E	package width	2.5	-	2.55	2.6	mm
A	seated height	0.55	-	0.6	0.65	mm
A ₂	package height	0.34	-	0.36	0.38	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	20	-	



2. Package outline

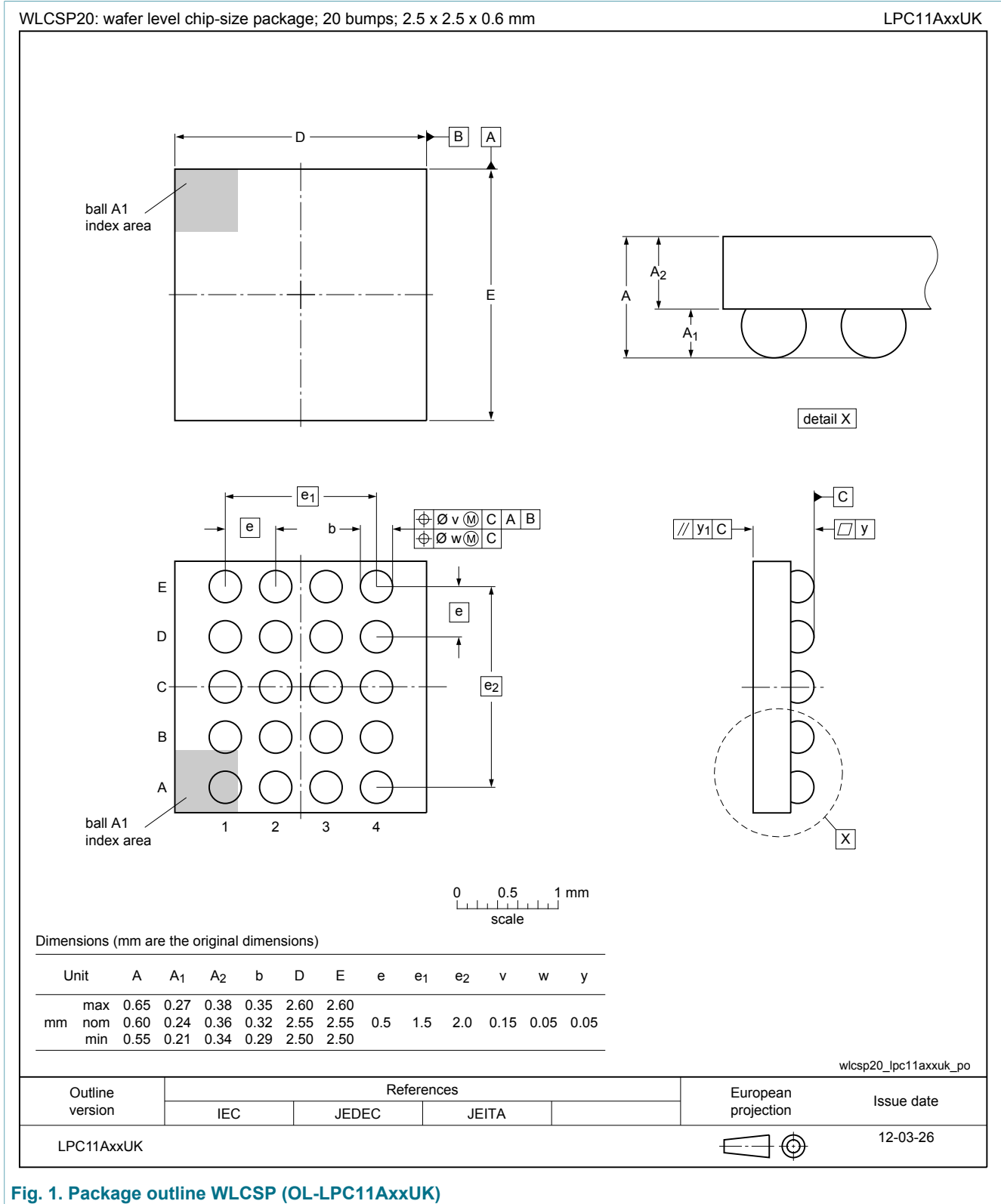


Fig. 1. Package outline WLCSP (OL-LPC11AxxUK)

3. Legal information

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